Packaging Foundry Services

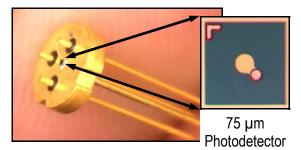
Complete Prototyping & Manufacturing Solutions for Optoelectronic Products

Design & Characterization

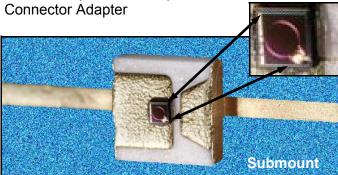
- Package design & material selection
 - CAD design, optical modeling (ray tracing & thin films), thermal modeling, RF modeling
- Material characterization
 - Visual & dimensional
 - Material analysis
- Complete electrical & optical testing

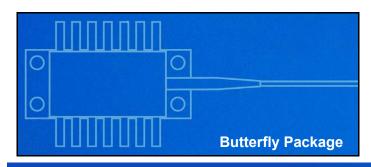
Assembly

- Die singulation
 - Scribe & cleave
 - Die sorting
- Die & substrate attach
 - Epoxy, alloy
 - Epoxy & alloy
- Specialized cleaning
 - Ultrasonic, spray, plasma



TO Packages: Window Cap, Lensed Cap,







Specificabile www.spectrolab.com

Assembly

- Wire bonding & ribbon welding
 - Wire wedge (manual & auto), wire ball (manual)
 - Ribbon welding
- Fiber preparation & alignment
 - Cleaving, splicing, alignment
- Hermetic sealing
 - Cap weld, seam seal
 - Alloy seal



The information contained on this sheet is for reference only. Actual specifications for delivered products may vary. 2/21/02

Process Characterization & Reliability Per Mil-Standard and Telcordia Standard

- Die shear
- Wire pull testing
- Hermeticity testing
 - Gross leak testing
 - Fine leak testing (He)
- Temperature cycling
- Accelerated aging
- Vibration
- Shock
- Damp heat
- Burn-in



SPECTROLAB

A BOEING COMPANY

IS09001:2000